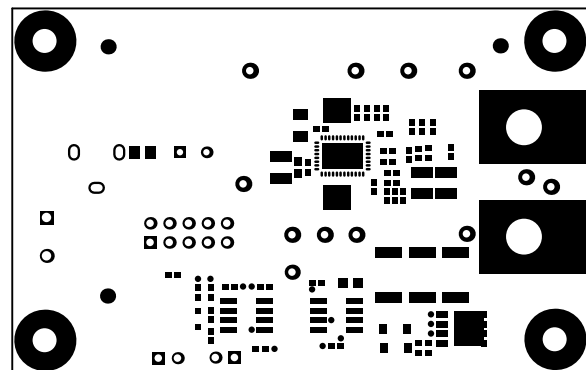
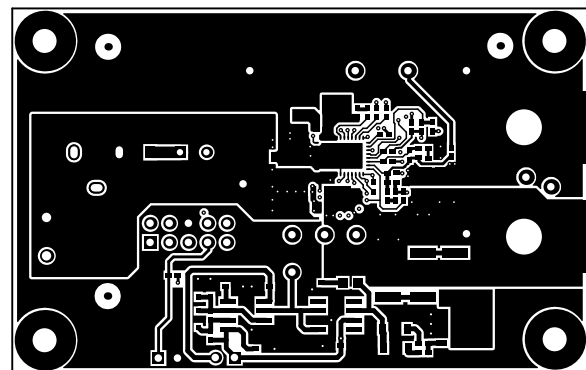


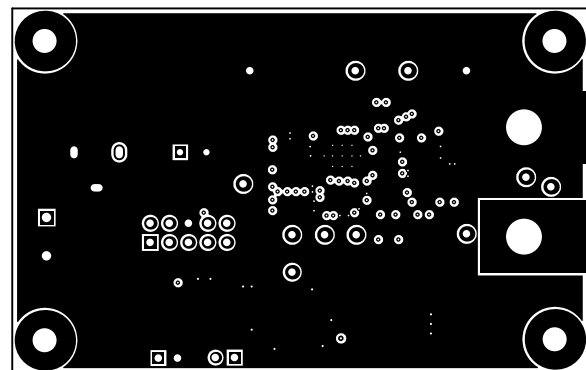
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/29/2016 4:11:08 PM	TEXAS INSTRUMENTS	



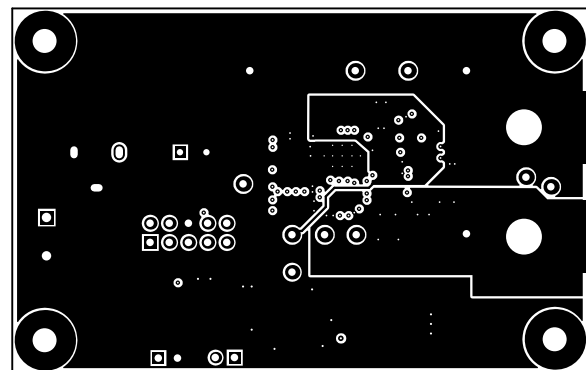
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/29/2016 4:11:08 PM	TEXAS INSTRUMENTS	



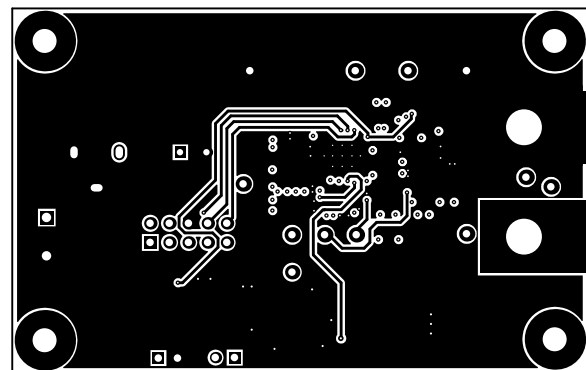
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/29/2016 4:11:09 PM	TEXAS INSTRUMENTS	



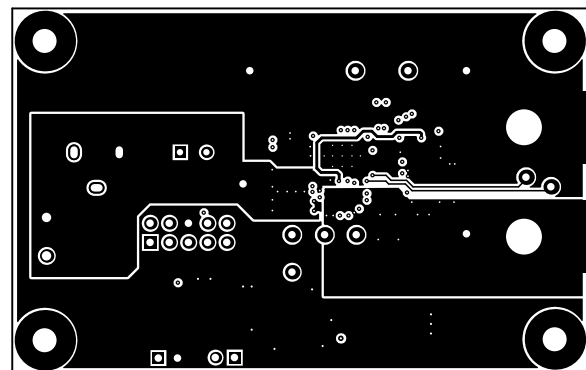
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 3/29/2016 4:11:10 PM	TEXAS INSTRUMENTS	



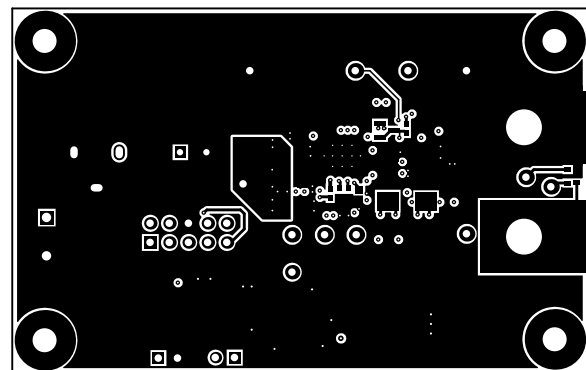
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 3/29/2016 4:11:10 PM	TEXAS INSTRUMENTS	



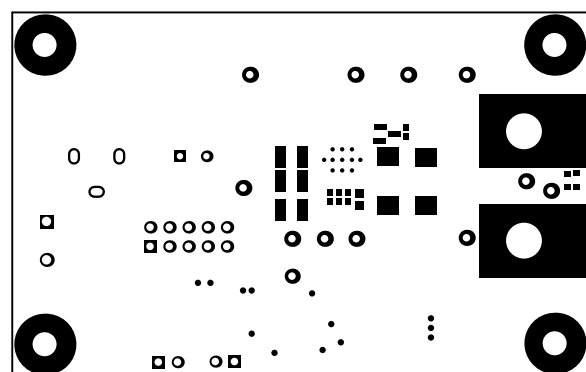
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 3	GENERATED : 3/29/2016 4:11:11 PM	TEXAS INSTRUMENTS	



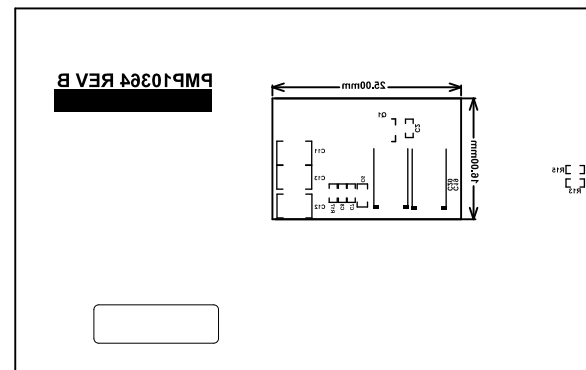
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 4	GENERATED : 3/29/2016 4:11:12 PM	TEXAS INSTRUMENTS	



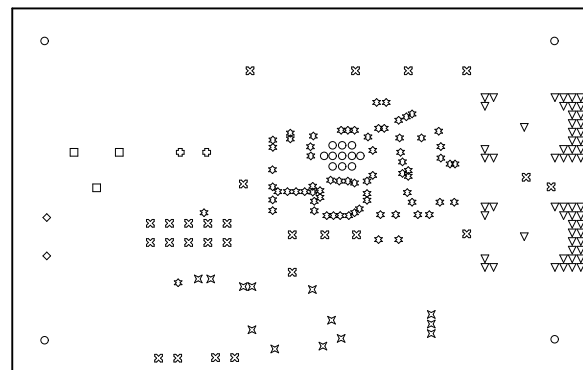
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/29/2016 4:11:12 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/29/2016 4:11:13 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/29/2016 4:11:14 PM	TEXAS INSTRUMENTS	

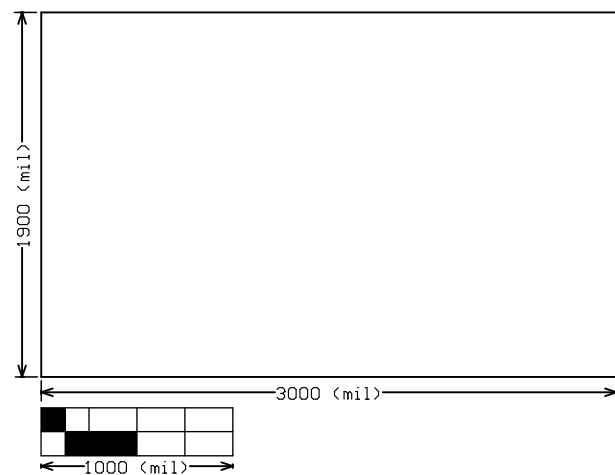


Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
○	11	7.874mil (0.2mm)			PTH	Round
✱	71	10mil (0.254mm)			PTH	Round
✕	13	12mil (0.305mm)			PTH	Round
▽	56	16mil (0.406mm)			PTH	Round
⊕	2	33.465mil (0.85mm)			PTH	Round
⊗	26	40mil (1.016mm)			PTH	Round
◇	2	49.213mil (1.25mm)			PTH	Round
○	4	125.984mil (3.2mm)			PTH	Round
▽	2	188mil (4.775mm)			PTH	Round
□	3	39.37mil (1mm)	62.992mil (1.6mm)	23.622mil (0.6mm)	PTH	Slot
	190 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
 Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/29/2016 4:11:14 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10364	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/29/2016 4:11:15 PM	TEXAS INSTRUMENTS	

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